

Heatsink

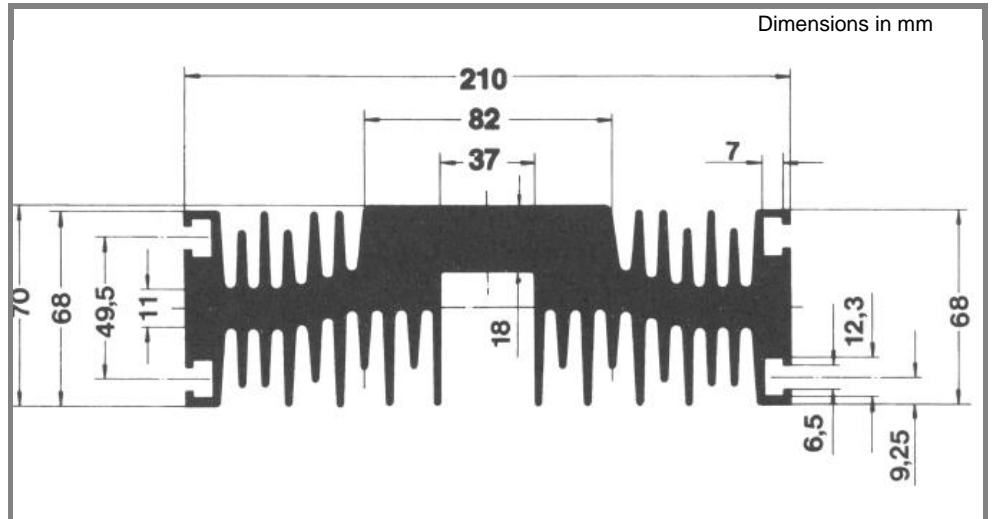
For capsule devices

P 9

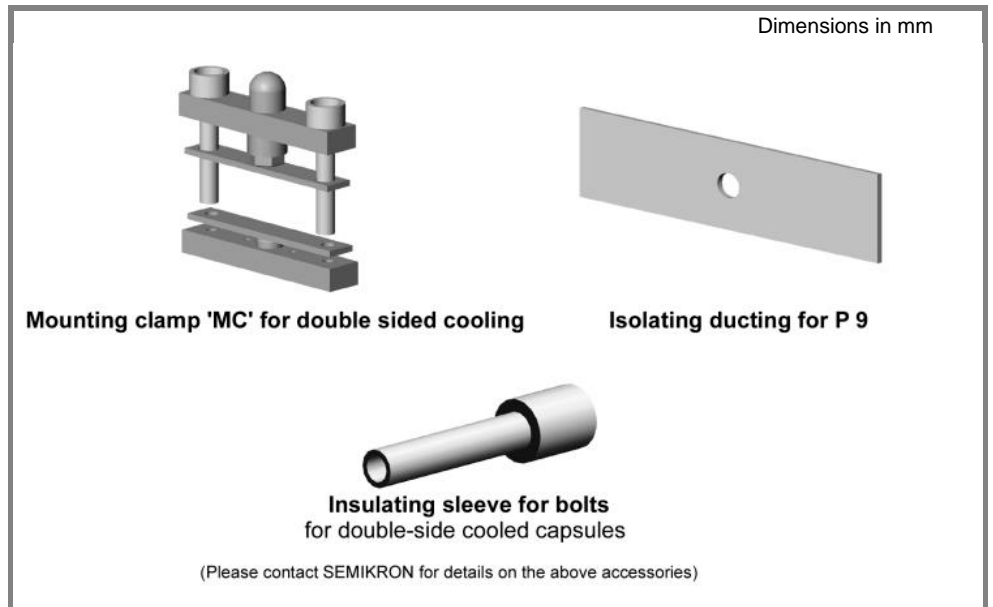
Features

- Intended for double-sided cooling of capsule devices with diameter upto 79mm
- Designed for natural or forced air cooling
- Available in various lengths

Standard lengths	n	b / d Ø mm	R _{thca} natural cooling K/W	R _{thca} V _{air} /t = 600 m ³ /h K/W	w kg
2x P 9/210		33 ± 2	0,215 (300 W)	0,065	8,2
P 9/430		48 ± 2	0,215 (300 W)	0,053	
+ 2x P9/210		33 ± 2		0,077	16,7
		48 ± 2		0,062	



P 9 general profile dimensions (w = 17,8 kg/m)



Mounting clamp 'MC' for double sided cooling

Isolating ducting for P 9

Insulating sleeve for bolts
for double-side cooled capsules

(Please contact SEMIKRON for details on the above accessories)

P 9 standard accessories

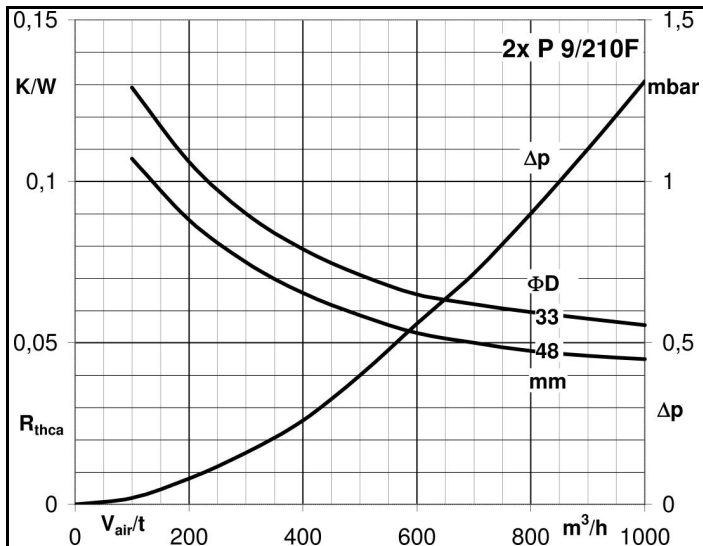


Fig.5a Thermal resistance and pressure drop vs. air flow

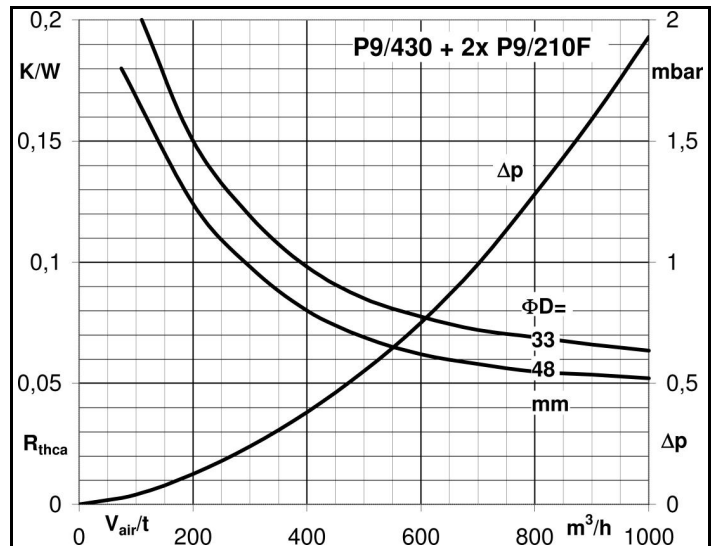


Fig.5b Thermal resistance and pressure drop vs. air flow (per device)

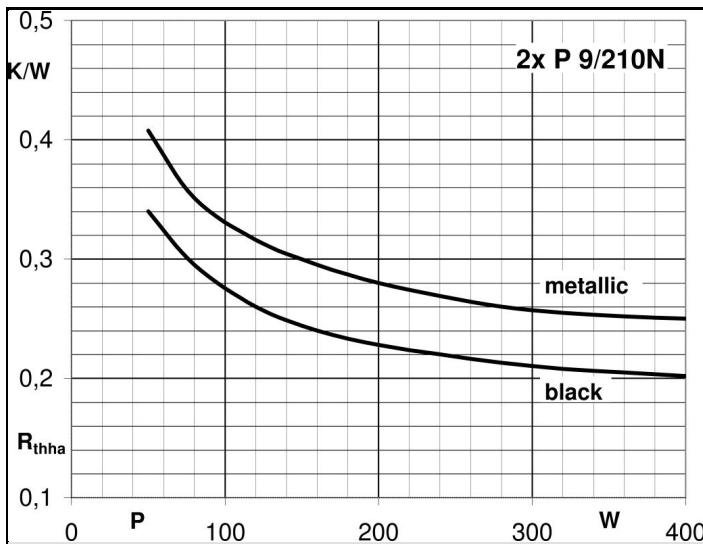


Fig.1 Thermal resistance vs. dissipated power

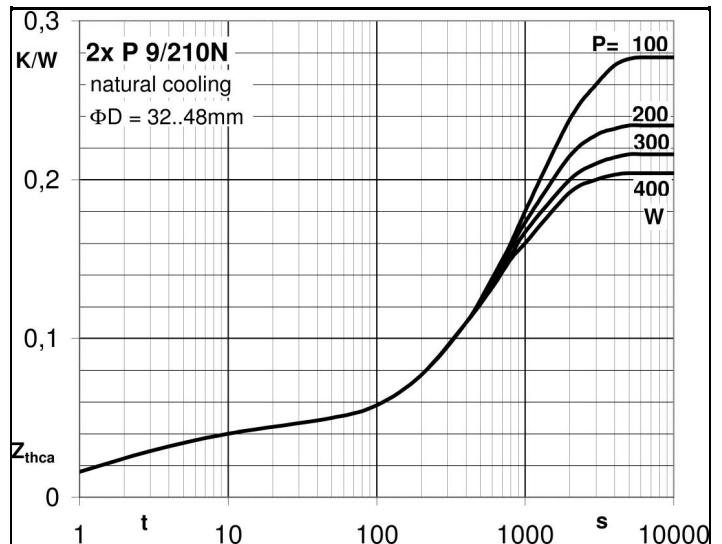


Fig.9 Transient thermal impedance vs. time

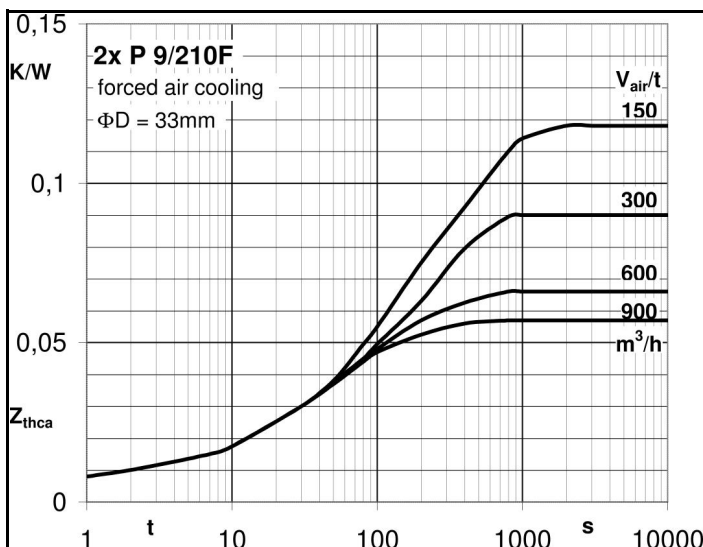


Fig.11a Transient thermal impedance vs. time

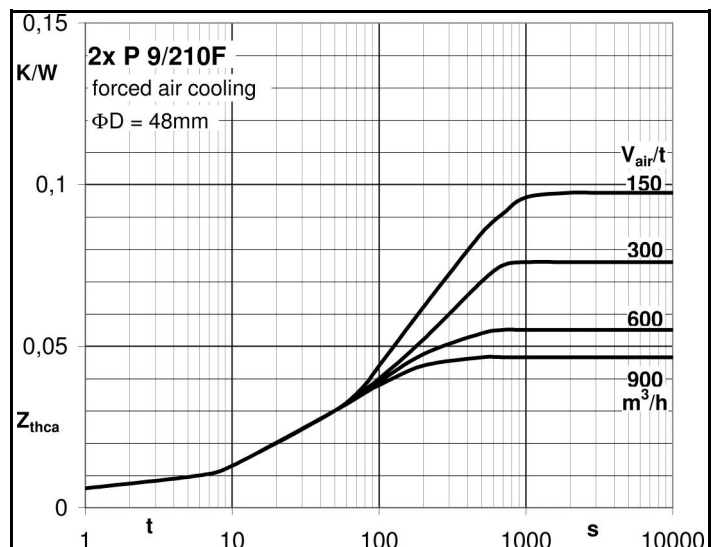
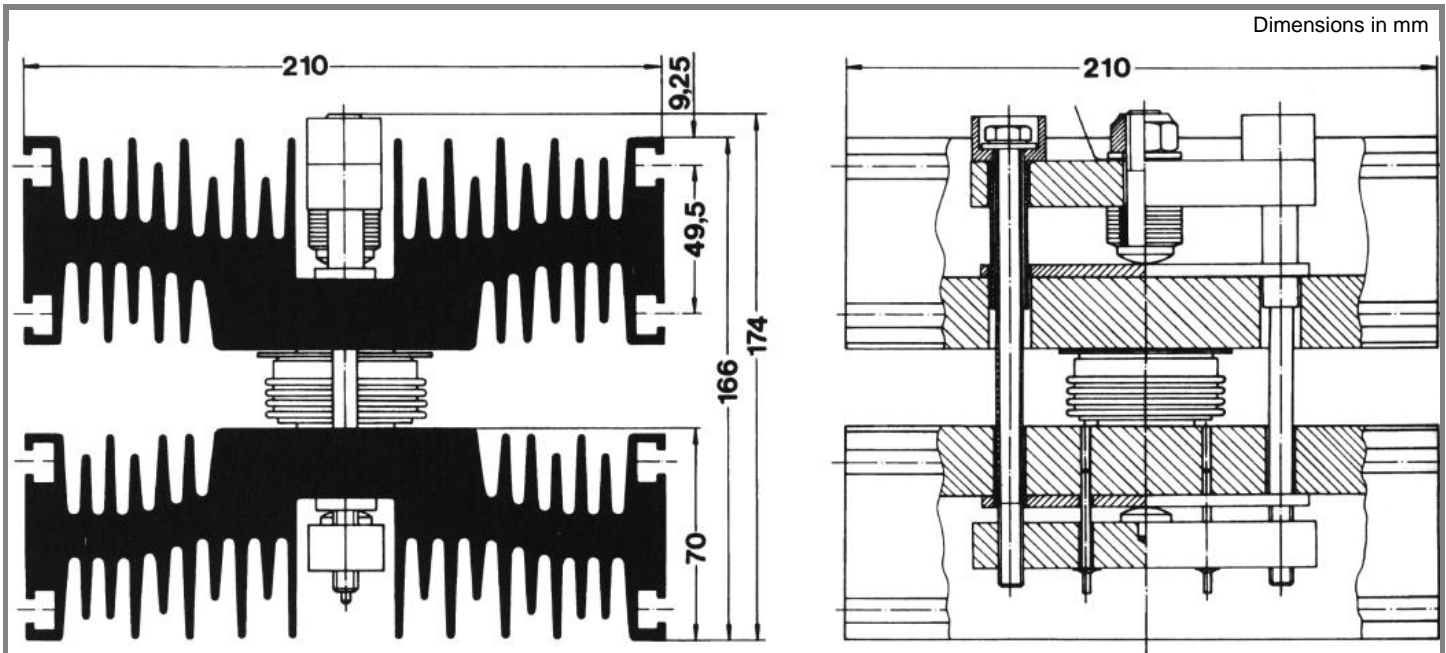


Fig.11b Transient thermal impedance vs. time



1. Setup example with a capsule mounted between 2x heatsink P9/210 using clamp type 'MC'